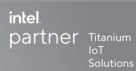
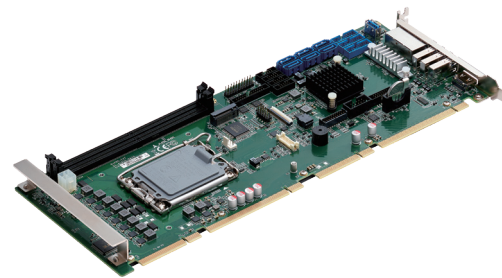


NuPRO-E47

PICMG[®] 1.3 Full-Size LGA1700 with
 12th Generation Intel[®] Core™ i9/i7/i5/i3
 Processor-based SHB



Features

- 12th Gen Intel[®] Core™ i7/i5/i3 processor
- Intel[®] Q670E Express chipset supporting PCI Express 3.0
- Two DIMM socket support up to 64 GB Non-ECC DDR5 4800 MHz
- Six SATA 3.0 onboard with RAID support
- Four COM ports (including RS-232/422/485)
- Intel[®] PCIe slot bifurcation support

Ordering Information

- NuPRO-E47
 PICMG[®] 1.3 Full-Size LG1700 with 12th Generation
 Intel[®] Core™ i9/i7/i5/i3 Processor-based SHB
 Note: CPU, Memory module and Cooler kit are not included

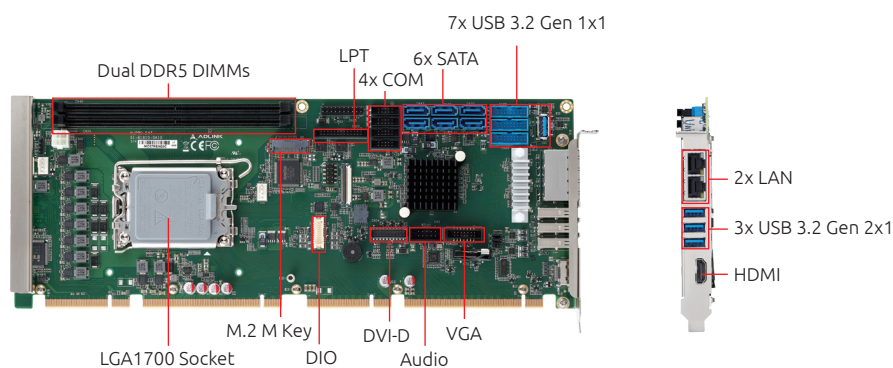
Packing Lists

- NuPRO-E47
- 2x SATA data cable
- 1x 2-port USB 3.0 cable with bracket
- 1x 2-port COM cable with bracket
- 1x print port cable with bracket

Optional Accessories

- | | |
|--|------------------|
| • DB-Audio2
High definition audio | 91-49030-0010 |
| • LGA1700 1U CPU cooler | 32-21002-0000-A0 |
| • LGA1700 2U CPU cooler | 32-20976-1000-A0 |
| • DVI-D/VGA cable with bracket | 30-25309-0000-A0 |
| • 4-port USB 3.0 cable with bracket | 30-25305-0020-A0 |
| • 2-port USB 3.0 cable (right angle)
with bracket | 30-25046-0110-A0 |
| • 1-port COM cable with bracket | 30-25003-2100 |
| • DIO cable with bracket | 30-25304-0000-B0 |

Product Illustration



Specifications

Processor System	CPU	Intel® Core™ i9-12900E, up to 5.0 GHz, 16 Cores, 30M Cache, 65W TDP Intel® Core™ i9-12900TE, up to 4.8 GHz, 16 Cores, 30M Cache, 35W TDP Intel® Core™ i7-12700E, up to 4.8 GHz, 12 Cores, 25M Cache, 65W TDP Intel® Core™ i7-12700TE, up to 4.7 GHz, 12 Cores, 25M Cache, 35W TDP Intel® Core™ i5-12500E, up to 4.5 GHz, 6 Cores, 18M Cache, 65W TDP Intel® Core™ i5-12500TE, up to 4.3 GHz, 6 Cores, 18M Cache, 35W TDP Intel® Core™ i3-12100E, up to 4.2 GHz, 4 Cores, 12M Cache, 60W TDP Intel® Core™ i3-12100TE, up to 4.0 GHz, 4 Cores, 12M Cache, 35W TDP Intel® Pentium® Gold G7400E, up to 3.6 GHz, 2 Cores, 6M Cache, 46W TDP Intel® Pentium® Gold G7400TE, up to 3.0 GHz, 2 Cores, 6M Cache, 35W TDP Intel® Celeron® G6900E, up to 3.0 GHz, 2 Cores, 4M Cache, 46W TDP Intel® Celeron® G6900TE, up to 2.4 GHz, 2 Cores, 4M Cache, 35W TDP
	Chipset	Intel® Q670E Express Chipset
	Memory	Dual-channel Non-ECC DDR5 4800 MHz, up to 64 GB
	BIOS	AMI® UEFI BIOS 256 Mbit SPI Flash Memory
	Watchdog Timer	1 to 65536 sec. software programmable and can be generate system reset
	Hardware Monitor	CPU temperature System temperature System voltage CPU fan speed
	Operating Systems	Microsoft® Windows® 10 64-bit Microsoft® Windows® 11 64-bit Ubuntu 20.04.06

Specifications

I/O Interfaces	M.2	1x M.2 M-Key, 2280, support PCIe Gen 4 x 4
	SATA	6x SATA 3.0 onboard with RAID support
	Serial Ports	2x RS-232 via onboard 2.0 pitch box header
		2x RS-232/422/485 with auto flow control via onboard 2.0 pitch box header
	Expansion Slots (Via backplane)	1x PCIe x16 with Intel® PCIe slot bifurcation support and can be configured to:
		1x PCIe x16 or 2x PCIe x8 to backplane (based on backplane)
		1 x PCIe x4 to backplane 4 x PCI to backplane
	USB	3x USB 3.2 Gen 2x1 ports (10Gbps) on rear I/O
		6x USB 3.2 Gen 1x1 via onboard box headers
		1x USB 3.2 Gen 1x1 vertical type A port
		4x USB 2.0 to backplane
	Parallel Port	1x LPT box header
	Audio	1x box header for audio module DB-Audio2
DIO	1x box header for 8-bit in and 8-bit out	
Ethernet	LAN1: Intel® I225-V via RJ45	
	LAN2: Intel® I225-LM via RJ45	
TPM	INFINEON TPM SLB 9670XQ2.0 or 9670VQ2.0	
Audio	Audio Codec	Realtek® ALC262 support by DB-Audio2 daughter board
	Interface	Intel® High Definition Audio via onboard box header
Graphics	Graphics	Integrated Intel® HD Graphics series, based on CPU for different GPU
	HDMI	1x HDMI on rear I/O, resolution up to 4096 x 2160 @ 60Hz
	DVI-D	1x DVI-D via onboard pin header, resolution up to 1920 x 1200 @ 60Hz
	VGA	1x VGA via onboard pin header, resolution up to 1920 x 1200 @ 60Hz
Mechanical and Environmental	Form Factor	Full-sized PICMG® 1.3 system Host Board
	Dimension	338 mm x 126 mm (L x W)
Relative Humidity	Operating Temperature	0 °C to 60 °C
	Storage Temperature	-40°C to 80°C
		5% to 95%, non-condensing
Certification		CE & FCC Class A